



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

ProCurve Switch 8212zl Chassis/Fan Tray (J9091A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx driver	T-10

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove any blank slot covers and modules from the front by unfastening the two screws found on each blank slot cover and modules. Refer to the respective modules product disassembly instructions to remove the components or material from the respective modules.
2. From the front, remove the power distribution PCA (7 slots – located on the left side within the chassis) by unfastening the 12 screws which secure it to the chassis. Remove the black insulator found behind the power distribution PCA.
3. From the front, remove the power distribution PCA (9 slots – located on the right side within the chassis) by unfastening the 14 screws which secure it to the chassis. Remove the black insulator found behind the power distribution PCA.
4. Remove the power supply unit(s)/blank cover(s) from the rear of the chassis by unfastening the respective screws (4 each).
5. Remove the fan tray (J9094A) from the rear of the chassis by unfastening the 4 screws which secure it to the chassis and pull it out. Refer to the J9094A product disassembly instructions to remove the components or material from the fan tray.
6. From the rear of the chassis, remove the power shelve from the bottom (which house 2 pieces of power bridging PCAs and the EPS PCA) by unfastening the 9 screws which secure it to the chassis and the backplane PCA.
7. Remove the 2 pieces of power bridging PCA from the power shelve by unfastening 4 screws each from the PCAs.
8. Remove the guide pin block from each of the power bridging PCA by unfastening the 1 screw located under the PCA.
9. Remove the EPS PCA from the bottom of the power shelve by unfastening 6 screws.
10. Remove the rear cover by unfastening the 10 screws which secure it to the chassis and the backplane PCA.
11. Remove the backplane from the rear of the chassis by unfastening the 32 screws which secure it to the chassis.
12. Remove the 17 guide pins from the backplane by unfastening the 17 screws which secured them to the backplane.

13. Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

